

1. GENERAL INFORMATION	Clean Track RF3 3 Coater 5 Developer w/ Steppert IF
Tool ID	CD68
Serial Number	T00505226A
Vintage	2007
OEM	SOKUDO
Model	RF-310A
Process	COAT/DEVE
Software version	Version 2.7.6.395 (OS : Windows NT4.0)
2. WAFER SPECIFICATION	
Wafer Size	200MM
Wafer Shape	SNNF (Semi Notch No Flat)
Wafer Cassette	8" PP Mirai
SMIF Interface	NO
3. SYSTEM CONFIGURATION	
Process Block#	2
Coater head#	3
Develop head#	5
Adhesion Chamber#	3
Cooling Plate#	6
Rapid Hot Plate(FRHP)#	16
EEW#	2
IFB#	1
Chemical Box (HMDS/Solvent/DIW/NMDW)	1
Controller Cabinet	1
Power BOX	1
Handling Unit Controller	2
3-1. Carrier Station	
Stage	1×4 Side Loading (Sender /Receiver)
3-2. Coater	
Nozzle#	7
Resist temperature System	1 temp control for 3 line x 3
Coater Cup	PP+PP+PP
Spin chuck	PEEK
Resist Pump	PDS-105C-KPM4-S01
Back rinse flow	flow meter with sensor
VPS Pluse Mist Nozzle flow	flow meter with sensor
Edge Cleaner	flow meter with sensor
Solvent solution supply	Central supply
Drain	Central
3-4. Developer	
Nozzle	Slit Scan Nozzle
Develop solution supply	Central supply
Developer Cup	PVC
Spin chuck	PEEK
Develop Nozzle Flow	flow meter with sensor
Develop Nozzle Wash	flow meter with sensor
Rinse Nozzle Flow	flow meter with sensor
Back Rinse Flow	flow meter with sensor
Develop temperature System	1 temp control for 1 line x 2
Drain	Central
3-5. Adhesion	
Method	Vapor prime by N2 Bubbling
Hot plate	60-150deg by 0.1deg pitch
HMDS solution supply	Central supply
3-7. Cooling Plate	
Method	Proximity bake with ceramic ball
Cooling plate	17-29deg by 0.1deg pitch
3-8. Rapid Hot Plate(FRHP)	
Method	Proximity bake with ceramic ball

Hot plate	70-180deg by 0.1deg pitch
3-9. EEW	
Lamp	Mercury xenon
Wave length	248nm
3-11. IFB	
Robot (BHU1)	1
Robot (BHU2)	1
Buffer	2



